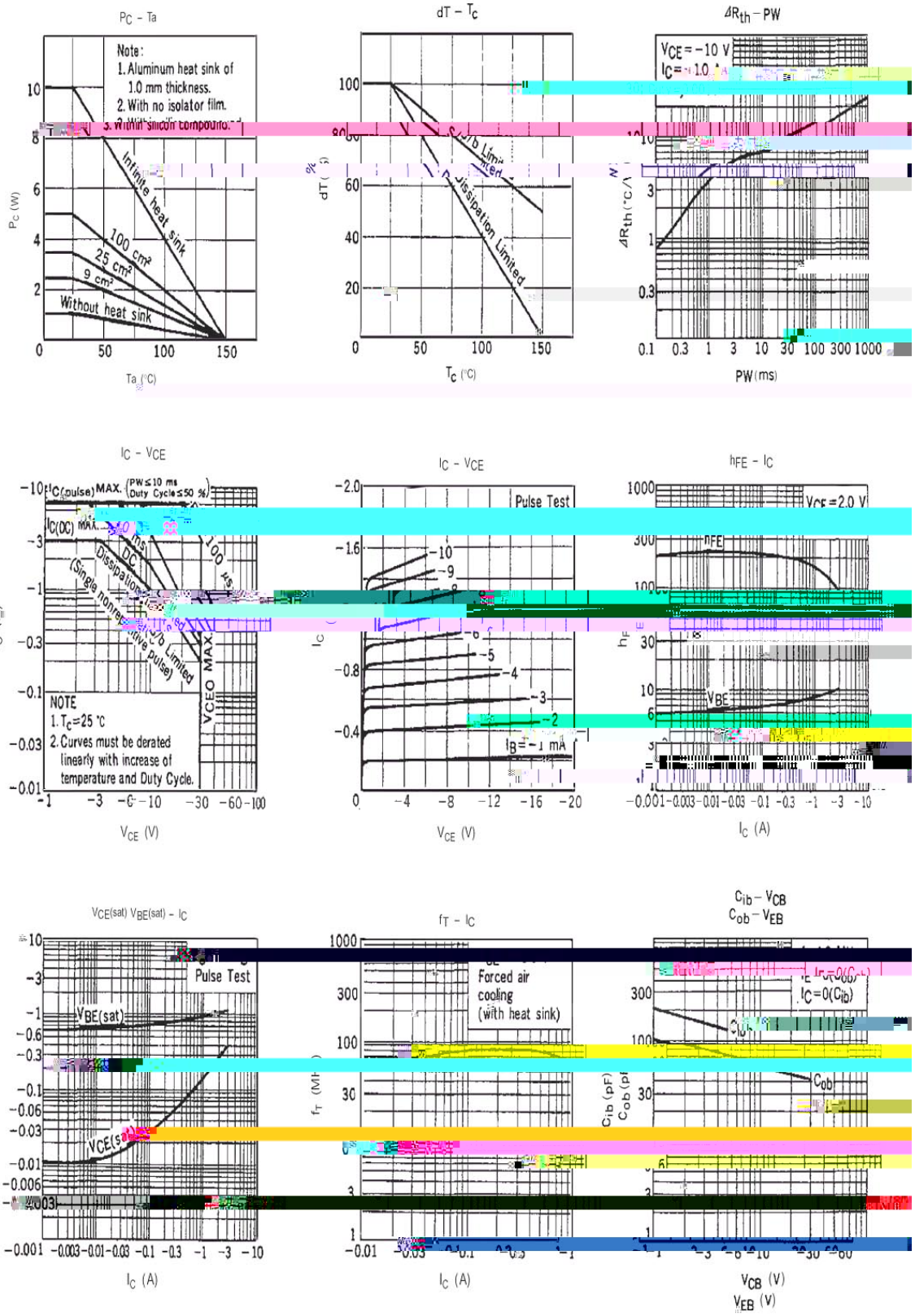
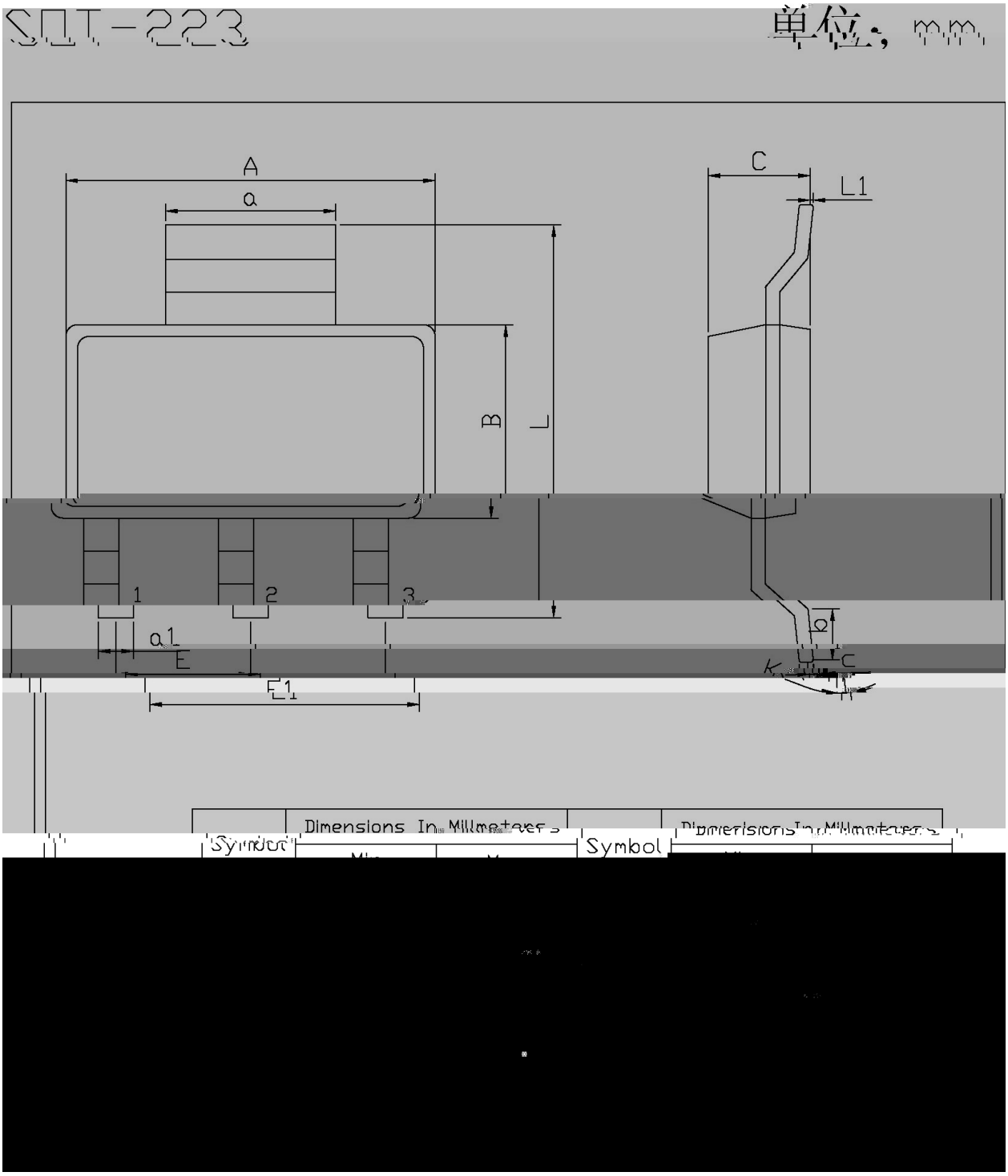
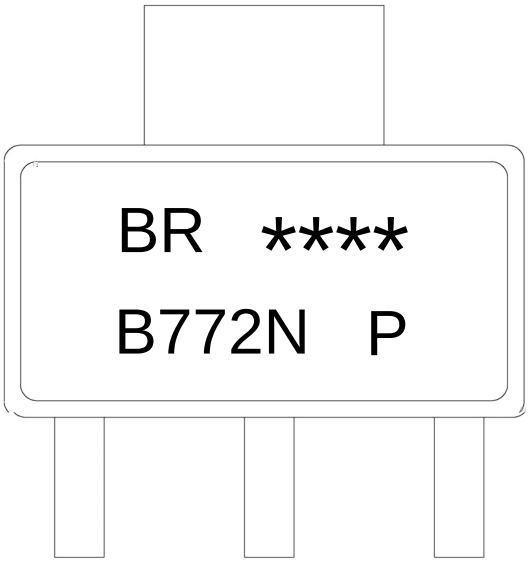
/ Electrical Characteristic Curve



/ Package Dimensions



/ Marking Instructions

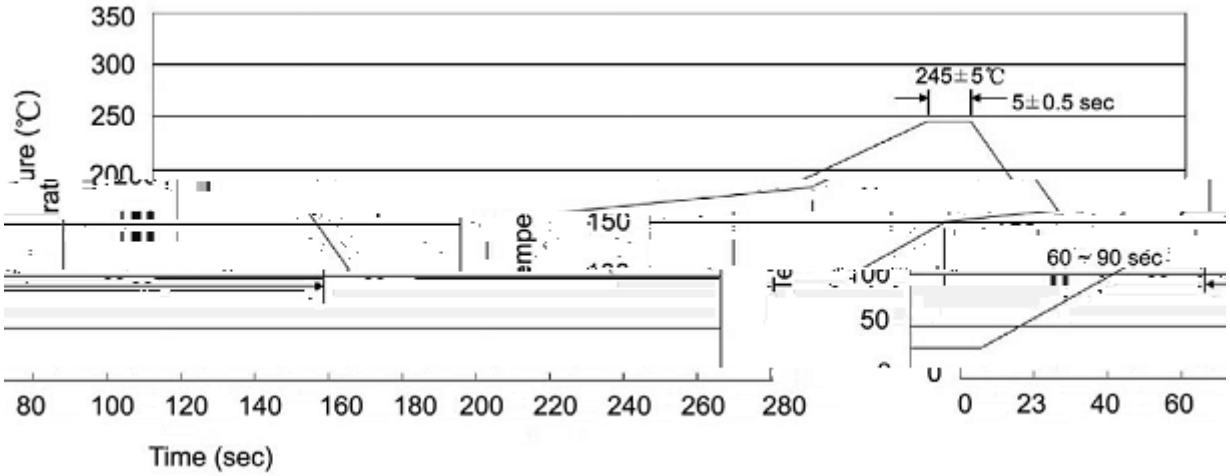


ب ″ χ	
BR χ	ﻫ ﺀ ﻧ ﮣ
B772N χ	ﻫ ﺯ ﻦ ﮣ
P χ	ﻫ h_{FE} ⁶ ﮣ
---- χ	ﻫ ﺍ ﻓ ﻍ ﻦ ﮣ ﺍ ﻏ ﺍ ﻓ ﻍ ﻦ Ψ ﻕ

Note:

BR:	Company Code.
B772N:	Product Type.
P:	h_{FE} Classifications Symbol
****:	Lot No. Code, code change with Lot No.

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



ب ˝ χ

1 Ĺ ♬ □ ỷ 25 Ḱ 150 ɬ ı `H ڑ 60 Ḱ 90sec;

2 Š Ë □ ỷ 245 ° 5 ɬ ı `H ڑ `Y ﾊ ㎛ 5 ° 0.5sec;

3 ì ˙ ﾘ ˛ ɔ ﻉ ỷ ㎛ 2 Ḱ 10 ɬ /sec.

Note:

1.Preheating:25~150 ɬ , Time:60~90sec.

2.Peak Temp.:245 ° 5 ɬ , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 ɬ /sec.

/ Resistance to Soldering Heat Test Conditions

□ ỷ χ 260 ° 5 ɬ	`H ڑ χ 10 ° 1 sec.	Temp:260±5	Time:10±1 sec

/ Packaging SPEC.

ɔ ` ﾔ Ł / REEL